Amendments to the Specification:

Please amend the following paragraph, which was inserted at the beginning of the specification by an amendment made in paragraph 18.b. of the Utility Patent Application Transmittal paper filed November 17, 2003:

This is a ☐ ~~Continuation~~ ☒ Divisional ☐ ~~Continuation-in-part (CIP)~~ application of Serial No. 09/473,414, filed December 28, 1999 (now U.S. Patent No. 6,827,584).

Please amend the paragraph that begins on page 23, line 22 as follows:

It should be appreciated that the structure shown in **Figure 1** is one embodiment of an interconnection element with the force applied in an inferior direction toward the surface of substrate 100 by, for example, an electronic component, to displace the interconnection element. In this embodiment, the contact region of interconnection element 110 is the superior surface of the end of interconnection element 110. Interconnection element 110 may alternatively be formed in a variety of shapes having different contact regions, such as illustrated in U.S. Patent Application No. ~~08/844,946,~~ 08/554,902 (now U.S. Patent No. 5,974,662), titled *"Probe Card Assembly and Kit and Methods of Using the Same."* The associated contact force and displacement of such interconnections will similarly vary.

Please amend the paragraph that starts on page 39, line 3 as follows:

At this point, structure 10 may be subjected to an optional heat treatment that, in one aspect, relieves stress in interconnection element 110, particularly at its anchor portion to secure its fixation to substrate 100, and improves the mechanical properties of spring material 140. Details concerning an optional heat treatment are described in detail in co-pending, commonly-assigned U.S. Patent Application No. 09/217,589, filed December 22, 1998 (now U.S. Patent No. 6,150,186), titled *"Method of Making a Product with Improved Material Properties by Moderate Heat Treatment of a Metal Incorporating a Dilute Additive,"* and corresponding PCT Application No. WO 99/14404, published March 25, 1999, incorporated herein by reference.

Please amend the paragraph that starts on page 39, line 15 as follows:

Figure 10 shows structure 10 after depositing travel stop material 160 over the structure. The fabrication and incorporation of various travel stops is described in co-pending, commonly-assigned U.S. Patent Application No. 09/032,473, filed July 13, 1998 (abandoned), titled *"Interconnect Assemblies and Methods,"* and U.S. Patent Application No. 09/264,788, filed July 30, 1999 (now U.S. Patent No. 6,120,082), titled *"Interconnect Assemblies and Methods,"* both of which are incorporated herein by reference. The following description sets forth one example of a suitable travel stop for the composite interconnection element. It will be appreciated that other travel stops described in the referenced and incorporated documents will generally also be suitable.